

IN THE CLAIMS:

Claims 2 through 16 have been amended herein. All of the pending claims 1 through 16 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A method for bonding a conductive element to a contact of a semiconductor device component, comprising:  
providing a semiconductor device component with at least one contact; and  
defining at least two layers of at least one conductive element from corresponding layers comprising substantially unconsolidated conductive material.
2. (Currently Amended) The method of claim 1, wherein ~~said~~-defining comprises causing said substantially unconsolidated conductive material in selected regions of each of said corresponding layers to at least partially consolidate.
3. (Currently Amended) The method of claim 1, further comprising, following ~~said~~ defining, permitting said substantially unconsolidated conductive material to at least partially consolidate.
4. (Currently Amended) The method of claim 1, wherein ~~said~~-providing said semiconductor device component comprises providing a carrier substrate.
5. (Currently Amended) The method of claim 1, wherein ~~said~~-providing said semiconductor device component comprises providing a semiconductor die.

6. (Currently Amended) The method of claim 1, wherein ~~said~~ providing said semiconductor device component comprises providing a packaged semiconductor device.

7. (Currently Amended) The method of claim 1, wherein ~~said~~ defining comprises defining said at least two layers from an at least partially liquified thermoplastic conductive elastomer.

8. (Currently Amended) The method of claim 7, further comprising, following ~~said~~ defining, permitting said at least partially liquified thermoplastic conductive elastomer to at least partially consolidate.

9. (Currently Amended) The method of claim 8, wherein ~~said~~ permitting said at least partially liquified thermoplastic conductive material elastomer to at least partially consolidate comprises permitting said at least partially liquified thermoplastic conductive material elastomer to at least partially harden.

10. (Currently Amended) The method of claim 1, wherein ~~said~~ defining comprises defining said at least two layers from an at least partially uncured conductive photopolymer.

11. (Currently Amended) The method of claim 10, wherein ~~said~~ defining comprises causing said at least partially uncured conductive photopolymer to at least partially consolidate.

12. (Currently Amended) The method of claim 11, wherein ~~said~~ causing said at least partially uncured conductive material photopolymer to at least partially consolidate comprises directing a laser beam onto selected regions of at least one of said corresponding layers of substantially unconsolidated conductive material.

13. (Currently Amended) The method of claim 1, wherein ~~said~~-defining comprises defining said at least two layers from metal particles.

14. (Currently Amended) The method of claim 13, wherein ~~said~~-defining comprises defining said at least two layers from resin-coated metal.

15. (Currently Amended) The method of claim 13, wherein ~~said~~-defining comprises securing said metal particles in selected regions of said corresponding layers of substantially unconsolidated conductive material to adjacent metal particles.

16. (Currently Amended) The method of claim 15, wherein ~~said~~-securing comprises directing an energy beam onto selected regions of said corresponding layers of substantially unconsolidated conductive material.

**IN THE DRAWINGS:**

The attached sheet of drawings includes a change to FIG. 12. This sheet replaces the original sheet including FIG. 12.

Specifically, FIG. 12 has been revised to lengthen the horizontal dashed line and add the reference numeral --188-- with appropriate lead line extending to the lengthened horizontal dashed line. No new matter has been added.